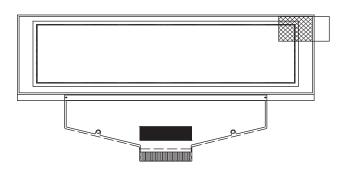


www.vishay.com Vishay

256 x 64 Graphic OLED



MECHANICAL DATA					
ITEM	UNIT				
Module dimension	88.0 x 27.8 x 2.05				
Viewing area	78.78 x 21.18				
Active area	76.778 x 19.178				
Dot size	0.278 x 0.278	mm			
Dot pitch	0.300 x 0.300				
Mounting hole	n/a				

FEATURES

Type: graphic

• Display format: 256 x 64 dots • Built-in controller: SSD1322

• Duty cycle: 1/64 • +3 V power supply

• Interface: I2C, 4-wire SPI, 6800, 8080

Without polarizer

· Material categorization: for definitions of compliance please see www.vishay.com/doc?99912

nu	JΠ	
COM	PLIAN	

ABSOLUTE MAXIMUM RATINGS					
ITEM	SYMBOL	STANDAF	UNIT		
I I EIVI	STIVIDOL	MIN.	MAX.	ONII	
Supply voltage for operation (1)(2)	V_{CI}	-0.3	4	>	
Supply voltage for logic (1)(2)	V_{DD}	-0.5	2.75	٧	
Supply voltage for I/O pins (1)(2)	$V_{\rm DDI/O}$	-0.5	V_{CI}	>	
Supply voltage for display (1)(2)	V _{CC}	-0.5	20	>	
Operating temperature	T _{OP} -40		+80	°C	
Storage temperature	T _{STG}	-40	+80		

Notes

 $^{(1)}$ All the above voltages are on the basis of "V_{SS} = 0 V"

When this module is used beyond the above absolute maximum ratings, permanent breakage of the module may occur. Also, for normal operations, it is desirable to use this module under the conditions according to "Electrical Characteristics". If this module is used beyond these conditions, malfunctioning of the module can occur and the reliability of the module may deteriorate

ELECTRICAL CHARACTERISTICS							
ITEM	CVMDOL	OVER THE CONTRICTION	ST	STANDARD VALUE			
ITEM	SYMBOL CONDITION —	MIN.	TYP.	MAX.	UNIT		
Supply voltage for logic	V _{CI}	(1)	2.8	3.0	3.3		
Supply voltage for display	V _{CC}	-	14	14.5	15		
High level input	V _{IH}	-	0.8 V _{DD}	-	V _{DDI/O}	V	
Low level input	V_{IL}	-	0	-	0.2 V _{DDI/O}	ľ	
High level output	V_{OH}	-	0.9 V _{DDI/O}	-	V _{DDI/O}		
Low level output	V _{OL}	-	0	-	0.1 V _{DDI/O}		
50 % check board operating current	I _{DD}	V _{CC} = 14.5 V	23	25	32	mA	

Note

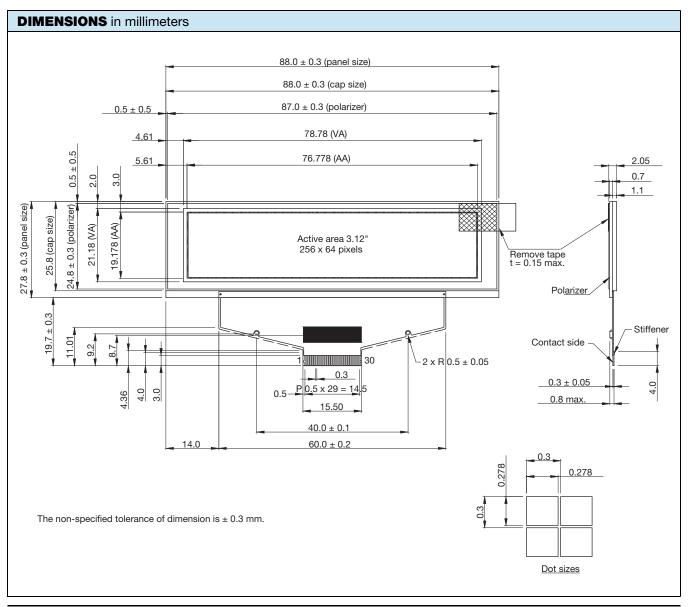
Supply voltage for logic = V_{DD} core power supply can be regulated from V_{CI}

OPTIONS				
		EMITTING COLOR		
YELLOW	GREEN	RED	BLUE	WHITE
Yes	-	-	-	-



	ACE PIN F		J			
PIN NO.	SYMBOL	I/O		FUNCTION		
POWER SI	UPPLY		T =			
26	V _{CI}	Р		Power supply for operation This is a voltage supply pin. It must be connected to external source and always be equal to or higher than V_{DD} and $V_{DDI/O}$		
25	V _{DD}	Р	This is a voltage supply pin. It ca	Power supply for core logic circuit This is a voltage supply pin. It can be supplied externally (within the range of 2.4 V to 2.6 V) or regulated internally from V_{CI} . A capacitor should be connected between this pin and V_{SS} under all		
24	V _{DDI/O}	Р		to V _{DDI/O} . When I/O signal pi	ed to V _{DD} or external source. All I/O ns (BS0 to BS1, D0 to D7, control	
2	V _{SS}	Р	Ground of logic circuit This is a ground pin. It also acts a ground	s a reference for the logic pin	s. It must be connected to external	
3, 29	V _{CC}	Р	Power supply for OLED panel These are the most positive volta source	ge supply pin of the chip. Th	ney must be connected to external	
5, 28	V _{LSS}	Р	Ground of analog circuit These are the analog ground pins.	They should be connected to	Vss externally	
DRIVER		<u> </u>	300 are the analog ground pins.		- 33 Satornary	
			Current reference for brightness ad	djustment		
22	I _{REF}	I	This pin is segment current reference pin. A resistor should be connected between this pin and V_{SS} . Set the current lower than 10 μA			
4	V _{COMH}	Р	Voltage output high level for COM signal This pin is the input pin for the voltage output high level for COM signals. A tantalum capacitor should be connected between this pin and $V_{\rm SS}$			
27	V _{SL}	Р	Voltage output low level for SEG signal This is segment voltage reference pin. When external V _{SL} is not used, this pin should be left open. When external V _{SL} is used, this pin should connect with resistor and diode to ground			
TESTING F	PADS					
21	FR	0	This pin is no connection pins. Not individually	hing should be connected to t	his pin. This pin should be left open	
			Communicating protocol select These pins are MCU interface sele	ection input. See the following	table:	
16	BS0			BS0	BS1	
			3-wire SPI	1	0	
		1 '	4-wire SPI	0	0	
17	BS1		8-bit 68XX parallel	1	1	
			8-bit 80XX parallel	0	1	
20	RES#	ı	Power reset for controller and drive This pin is reset signal input. When		the chip is executed	
19	CS#	I	This pin is reset signal input. When the pin is low, initialization of the chip is executed Chip select This pin is the chip select input. The chip is enabled for MCU communication only when CS# is pulled "low"			
18	D/C#	I	Data / command control This pin is data / command control pin. When the pin is pulled "high", the input at D7 to D0 is treated as display data. When the pin is pulled "low", the input at D7 to D0 will be transferred to the command register. For detail relationship to MCU interface signals, please refer to the timing characteristics diagrams			
14	E/RD#	ı	Read / write enable or read This pin is MCU interface input. When interfacing to a 68XX-series microprocessor, this pin will be used as the enable (E) signal. Read / write operation is initiated when this pin is pulled high and the CS# is pulled "low". When connecting to an 80XX-microprocessor, this pin receives the read (RD#) signal. Data read operation is initiated when this pin is pulled "low" and CS# is pulled "low". When serial mode is selected, this pin must be connected to V _{SS}			

INTERFA	INTERFACE PIN FUNCTION				
PIN NO.	SYMBOL	I/O	FUNCTION		
15	R/W#	1	Read / write select or write This pin is MCU interface input. When interfacing to a 68XX-series microprocessor, this pin will be used as read / write (R/W#) selection input. Pull this pin to "high" for read mode and pull it to "low" for write mode. When 80XX interface mode is selected, this pin will be the write (WR#) input. Data write operation is initiated when this pin is pulled "low" and the CS# is pulled "low". When serial mode is selected, this pin must be connected to VSS		
6 to 13	D7 to D0	I/O	Host data input / output bus These pins are 8-bit bi-directional data bus to be connected to the microprocessor's data bus. When serial mode is selected, D1 will be the serial data input SDIN and D0 will be the serial clock input SCLK. Unused pins must be connected to V _{SS} except for D2 in serial mode		
RESERVE					
23	NC	-	Reserved pin The NC pin between function pins are reserved for compatible and flexible design		
1, 30	NC (GND)	-	Reserved pin (supporting pin) The supporting pins can reduce the influences from stresses on the function pins. These pins must be connected to external ground		





MODULE CLA	SSIFICATION INFORMA	ATION				
OLED -	256 Y 064 B	- L P P 3 N 0 0 000				
1	2 3 4 5	6 7 8 9 10 11 12 13				
1	Brand	Vishay Intertechnology, Inc.				
2	Horizontal format	256 columns				
		F: COG type, with frame				
		H: graphic type				
3	Display type	N: character type				
		O: COG type				
		Y: tab type				
4	Vertical format	64 lines				
5	Serials code	В				
		A: amber				
		B: blue				
		C: full color				
		G: green				
6	Emitting color	L: yellow				
		R: red				
		S: sky blue				
		W: white				
		X: yellow / sky blue (dual color)				
		Y: yellow green				
7	Polarizer	N: without polarizer P: with polarizer				
		A: active matrix				
8	Display mode	P: passive matrix				
		3: 3.0 V to 3.3 V				
9	Driver voltage	5: 5.0 V				
		N: without touch panel				
10	Touch panel	T: with touch panel				
		0: standard				
		1: sunlight readable				
11	Products type	2: transparent OLED (TOLED)				
		3: flexible OLED				
		4: OLED for lighting				
		0: standard (A level)				
		2: B level				
12	Product grades	3: C level				
		4: high class (AA level)				
		5: customer offerings				
13	Serial number	Application serial number (000 to ZZZ)				



Vishay

GENERAL SPECIFICATIONS					
ITEM DIMENSION U					
Dot matrix	256 x 64				
Module dimension	88.0 x 27.8 x 2.05	mm			
Viewing area	78.78 x 21.18	mm			
Active area	76.778 x 18.178	mm			
Dot size	0.278 x 0.278				
Dot pitch	ch 0.300 x 0.300				
Display mode	Passive matrix				
Display color	Yellow				
Drive duty	1/64				
IC	SSD1322				

FUNCTION BLOCK DIAGRAM

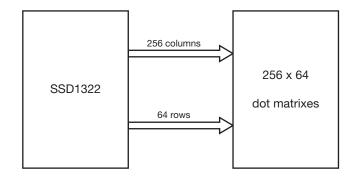
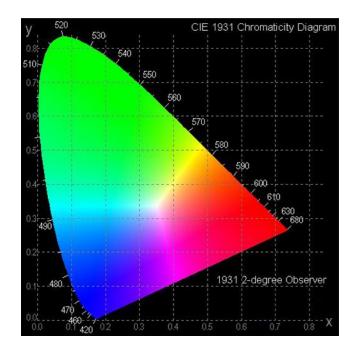


Fig. 1

Note

 For more information, please refer to Application Note provided by Vishay

OPTICAL CHARACTERISTICS						
ITEM	SYMBOL	CONDITION	MIN.	TYP.	MAX.	UNIT
View andle	(V)θ		160	-	-	doa
View angle	(H)φ		160	=	-	deg
Contrast ratio	CR	Dark	2000 : 1	-	-	-
Deep and time	t _{rise}		-	10	-	μs
Response time	t _{fall}		-	10	-	μs
Display with 50 % check board brightness			100	120	-	cd/m ²
CIE _x (yellow)	(CIE1931)		0.45	0.47	0.49	
CIE _y (yellow)	(CIE1931)		0.48	0.50	0.52	





Vishay

OLED LIFETIME			
ITEM	CONDITIONS	MIN.	TYP.
Operating life time	T _A = 25 °C, initial 50 % check board brightness typical value	50 000 h	-

Notes

- Life time is defined the amount of time when the luminance has decayed to < 50 % of the initial value
- This analysis method uses life data obtained under accelerated conditions to extrapolate an estimated probability density function (PDF) for the product under normal use conditions
- Screen saving mode will extend OLED lifetime

RELABILITY			
ENVIRONMENTAL TEST			
TEST ITEM	CONTENT OF TEST		TEST CONDITION
High temperature storage	Endurance test applying the high storage temperal long time	ture for a	80 °C, 240 h
Low temperature storage	Endurance test applying the low storage temperal long time	ture for a	-40 °C, 240 h
High temperature operation	Endurance test applying the electric stress (vo current) and the thermal stress to the element for a	tage and long time	80 °C, 240 h
Low temperature operation	Endurance test applying the electric stress u temperature for a long time	nder low	-40 °C, 240 h
High temperature / humidity storage	Endurance test applying the high temperature humidity storage for a long time	and high	60 °C, 90 % RH, 240 h
Temperature cycle		ture cycle	-40 °C / 80 °C, 100 cycles
	1 cycle		
MECHANICAL TEST		•	
Vibration test	Endurance test applying the vibration during tran- and using	sportation 10	0 Hz to 22 Hz for 1.5 mm peak-to-peak, 22 Hz to 500 Hz for 1.5 g, total 0.5 h
Shock test	Constructional and mechanical endurance test ap shock during transportation	plying the	50 g half sin wave 11 ms, 3 times of each direction
Atmospheric pressure test	Endurance test applying the atmospheric pressu transportation by air	ire during	115 mbar, 40 h
OTHERS			
Static electricity test	Endurance test applying the electric stress to the t	erminal	$V_S = \pm~600~V$ (contact), $\pm~800~V$ (air), $R_S = 330~\Omega$, $C_S = 150~pF$, 10 times

Note

• Supply voltage for OLED system = operating voltage at 25 °C

TEST AND MEASUREMENT CONDITIONS

- 1. All measurements shall not be started until the specimens attain to temperature stability. After the completion of the described reliability test, the samples were left at room temperature for 2 hours prior to conducting the failure test at 23 °C \pm 5 °C, 55 % \pm 15 % RH
- 2. All-pixels-on is used as operation test pattern
- 3. The degradation of polarizer are ignored for high temperature storage, high temperature / humidity storage, temperature cycle

EVALUATION CRITERIA

- 4. The function test is OK
- 5. No observable defects
- 6. Luminance: > 50 % of initial value
- 7. Current consumption: within ± 50 % of initial value

APPENDIX: RESIDUE IMAGE

Because the pixels are lighted in different time, the luminance of active pixels may reduce or differ from inactive pixels. Therefore, the residue image will occur. To avoid the residue image, every pixel needs to be lighted up uniformly.



INSPECTION SPECIFICATION						
NO.	ITEM		CRITERIO	N		AQL
01	Electrical testing Black or white	1.1 Missing vertical, horizontal segment, segment contrast defect 1.2 Missing character, dot or icon 1.3 Display malfunction 1.4 No function or no display 1.5 Current consumption exceeds product specifications 1.6 OLED viewing angle defect 1.7 Mixed product types 1.8 Contrast defect			0.65	
02	spots on OLED (display only)	 2.1 White and black spots on display ≤ 0.25 mm, no more than three white or black spots present 2.2 Densely spaced: no more than two spots or lines within 3 mm 			2.5	
03	OLED black spots, white spots, contamination (non-display)	3.1 Round type: as following $\Phi = (x + y) / 2$ $\Rightarrow x \mid x \mid y$	drawing	SIZE $\Phi \le 0.10$ $0.10 < \Phi \le 0.20$ $0.20 < \Phi \le 0.25$ $0.25 < \Phi$	ACCEPTABLE QTY Accept no dense 2 1 0	2.5
		3.2 Line type (as following drawing)	LENGTH - L≤3.0 L≤2.5 -	$\begin{tabular}{c} \textbf{WIDTH} \\ W \le 0.02 \\ 0.02 < W \le 0.03 \\ 0.03 < W \le 0.05 \\ 0.05 < W \\ \end{tabular}$	ACCEPTABLE QTY Accept no dense 2 As round type	2.5
04	Polarizer bubbles	If bubbles are visible, judge specifications, not easy to fin specify direction.		SIZE Φ $\Phi \le 0.20$ $0.20 < \Phi \le 0.50$ $0.50 < \Phi \le 1.00$ $1.00 < \Phi$ Total QTY	ACCEPTABLE QTY Accept no dense 3 2 0 3	2.5
05	Scratches	Follow no. 3 OLED black spots, white spots, contamination				
06	Chipped glass	Symbols: x: chip length k: seal width l: electrode pad length 6.1 General glass chip: 6.1.1 Chip on panel surface and z: chip thickness z ≤ 1/2 t 1/2 t < z ≤ 2 t Note	y: chip width t: glass thickness d crack between pane y y: chip width Not over viewing a Not exceed 1/3 k	x y z	z: chip thickness a: OLED side length	2.5



NO	PECTION SPEC	JIFICATION	ODITEDION		1 40
NO.	ITEM	6.1.2 Corner crack:	CRITERION		AC
06	Chipped glass	U.T.2 COME CLACK.	X Z Z Y		2.
		z: chip thickness	y: chip width	x: chip length	1
		$z \le 1/2 t$	Not over viewing area	x. chip length x ≤ 1/8 a	1
		1/2 t < z ≤ 2 t	Not exceed 1/3 k	x ≤ 1/8 a	1
		, <u> </u>	Not exceed 1/3 K	X ≥ 1/0 a	J
		Note • If there are 2 or more chips, x is total length of each chip			
		Symbols:			
		x: chip length	y: chip width	z: chip thickness	
		k: seal width	t: glass thickness	a: OLED side length	
		I: electrode pad length 6.2 Protrusion over term 6.2.1 Chip on electrode pa			
			× ×	z	
		y: chip width	x: chip length	z: chip thickness	1
		y ≤ 0.5 mm	x ≤ 1/8 a	0 < z ≤ t	
		6.2.2 Non-conductive port	· · · · · · · · · · · · · · · · · · ·		J
06	Glass crack	y z			. 2.
		y: chip width	x: chip length	z: chip thickness	1
		y ≤ l	x ≤ 1/8 a	0 < z ≤ t	
		according to electrode te	sealed by the customer, the alignment		d]
			y ≤ 1/3 l	x ≤ a]





INSPECTION SPECIFICATION				
NO. ITEM		CRITERION		
		8.1 Illumination source flickers when lit	0.65	
08	Backlight elements	8.2 Spots or scratched that appear when lit must be judged. Using OLED spot, lines and contamination standards	2.5	
		8.3 Backlight does not light or color wrong	0.65	
09	Bezel	9.1 Bezel may not have rust, be deformed or have fingerprints, stains or other contamination	2.5	
09	Dezei	9.2 Bezel must comply with job specifications	0.65	
		10.1 COB seal may not have pinholes larger than 0.2 mm or contamination	2.5	
		10.2 COB seal surface may not have pinholes through to the IC	2.5	
		10.3 The height of the COB should not exceed the height indicated in the assembly diagram	0.65	
		10.4 There may not be more than 2 mm of sealant outside the seal area on the PCB. And there should be no more than three places	2.5	
10	PCB, COB	10.5 No oxidation or contamination PCB terminals	2.5	
		10.6 Parts on PCB must be the same as on the production characteristic chart. There should be no wrong parts, missing parts or excess parts	0.65	
		10.7 The jumper on the PCB should conform to the product characteristic chart	0.65	
		10.8 If solder gets on bezel tab pads, OLED pad, zebra pad or screw hold pad, make sure it is smoothed down	2.5	
		11.1 No un-melted solder paste may be present on the PCB	2.5	
11	Caldarias	11.2 No cold solder joints, missing solder connections, oxidation or icicle	2.5	
11	Soldering	11.3 No residue or solder balls on PCB	2.5	
		11.4 No short circuits in components on PCB	0.65	
		12.1 No oxidation, contamination, curves or, bends on interface pin (OLB) of TCP	2.5	
		12.2 No cracks on interface pin (OLB) of TCP	0.65	
		12.3 No contamination, solder residue or solder balls on product	2.5	
		12.4 The IC on the TCP may not be damaged, circuits	2.5	
	General appearance	12.5 The uppermost edge of the protective strip on the interface pin must be present or look as if it cause the interface pin to sever	2.5	
12		12.6 The residual rosin or tin oil of soldering (component or chip component) is not burned into brown or black color	2.5	
		12.7 Sealant on top of the ITO circuit has not hardened	2.5	
		12.8 Pin type must match type in specification sheet	0.65	
		12.9 OLED pin loose or missing pins	0.65	
		12.10 Product packaging must the same as specified on packaging specification sheet	0.65	
		12.11 Product dimension and structure must conform to product specification sheet	0.65	



CHECK ITEM	CLASSIFICATION	CRITERIA
No display	Major	
Missing line	Major	
Wissing line		
Pixel short	Major	
Darker short	Major	
Wrong display	Major	
Un-uniform	Major	
B/A x 100 % < 70 % A/C x 100 % < 70 %		A Normal B Dark pixel C Light pixel

Vishay

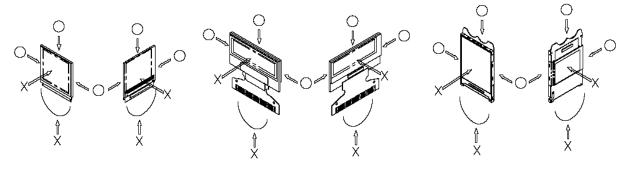
PRECAUTIONS IN USE OF OLED MODULES

MODULES

- 1. Avoid applying excessive shocks to module or making any alterations or modifications to it
- 2. Do not make extra holes on the printed circuit board, modify its shape or change the components of OLED display module
- 3. Do not disassemble the OLED display module
- 4. Do not operate it above the absolute maximum rating
- 5. Do not drop, bend or twist OLED display module
- 6. Soldering: only to the I/O terminals
- 7. Storage: please storage in anti-static electricity container and clean environment
- 8. It is pretty common to use "screen saver" to extend the lifetime and do not use fix information for long time in real application
- 9. Do not use fixed information in OLED panel for long time, that will extend "screen burn" effect time
- 10. Vishay has the right to change the passive components, including R2 and R3 adjust resistors. (Resistors, capacitors, and other passive components will have different appearance and color caused by the different supplier)
- 11. Vishay have the right to change the PCB Rev. (In order to satisfy the supplying stability, management optimization, and the best product performance... etc, under the premise of not affecting the electrical characteristics and external dimensions, Vishay have the right to modify the version)

HANDLING PRECAUTIONS

- 1. Since the display panel is being made of glass, do not apply mechanical impacts such us dropping from a high position
- 2. If the display panel is broken by some accident and the internal organic substance leaks out, be careful not to inhale nor lick the organic substance
- 3. If pressure is applied to the display surface or its neighborhood of the OLED display module, the cell structure may be damaged and be careful not to apply pressure to these sections
- 4. The polarizer covering the surface of the OLED display module is soft and easily scratched. Please be careful when handling the OLED display module
- 5. When the surface of the polarizer of the OLED display module has soil, clean the surface. It takes advantage of by using following adhesion tape
- Scotch mending tape no. 810 or an equivalent
 Never try to breathe upon the soiled surface nor wipe the surface using cloth containing solvent such as ethyl alcohol, since
 the surface of the polarizer will become cloudy. Also, pay attention that the following liquid and solvent may spoil the
 polarizer:
 - Water
 - Ketone
 - Aromatic solvents
- 6. Hold OLED display module very carefully when placing OLED display module into the system housing. Do not apply excessive stress or pressure to OLED display module. And, do not over bend the film with electrode pattern layouts. These stresses will influence the display performance. Also, secure sufficient rigidity for the outer cases



- 7. Do not apply stress to the LSI chips and the surrounding molded sections
- 8. Do not disassemble nor modify the OLED display module
- 9. Do not apply input signals while the logic power is off

VISHAY.

OLED-256Y064B-LPP3N00000

Vishay

OLED-2301004B-LPP3N0000

10. Pay sufficient attention to the working environments when handing OLED display modules to prevent occurrence of element breakage accidents by static electricity

- Be sure to make human body grounding when handling OLED display modules
- Be sure to ground tools to use or assembly such as soldering irons

www.vishay.com

- To suppress generation of static electricity, avoid carrying out assembly work under dry environments
- Protective film is being applied to the surface of the display panel of the OLED display module. Be careful since static
 electricity may be generated when exfoliating the protective film
- 11. Protection film is being applied to the surface of the display panel and removes the protection film before assembling it. At this time, if the OLED display module has been stored for a long period of time, residue adhesive material of the protection film may remain on the surface of the display panel after removed of the film. In such case, remove the residue material by the method introduced in the above no. 5
- 12. If electric current is applied when the OLED display module is being dewed or when it is placed under high humidity environments, the electrodes may be corroded and be careful to avoid the above

STORAGE PRECAUTIONS

- 1. When storing OLED display modules, put them in static electricity preventive bags avoiding exposure to direct sun light nor to lights of fluorescent lamps and, also, avoiding high temperature and high humidity environment or low temperature (less than 0 °C) environments. We recommend you to store these modules in the packaged state when they were shipped from Vishay. At that time, be careful not to let water drops adhere to the packages or bags nor let dewing occur with them
- 2. If electric current is applied when water drops are adhering to the surface of the OLED display module, when the OLED display module is being dewed or when it is placed under high humidity environments, the electrodes may be corroded and be careful about the above

DESIGNING PRECAUTIONS

- 1. The absolute maximum ratings are the ratings which cannot be exceeded for OLED display module, and if these values are exceeded, panel damage may be happen
- 2. To prevent occurrence of malfunctioning by noise, pay attention to satisfy the V_{IL} and V_{IH} specifications and, at the same time, to make the signal line cable as short as possible
- 3. We recommend you to install excess current preventive unit (fuses, etc.) to the power circuit (VDD) (recommend value: 0.5 A)
- 4. Pay sufficient attention to avoid occurrence of mutual noise interference with the neighboring devices
- 5. As for EMI, take necessary measures on the equipment side basically
- 6. When fastening the OLED display module, fasten the external plastic housing section
- 7. If power supply to the OLED display module is forcibly shut down by such errors as taking out the main battery while the OLED display panel is in operation, we cannot guarantee the quality of this OLED display module
 - Connection (contact) to any other potential than the above may lead to rupture of the IC

PRECAUTIONS WHEN DISPOSING OF THE OLED DISPLAY MODULES

1. Request the qualified companies to handle industrial wastes when disposing of the OLED display modules. Or, when burning them, be sure to observe the environmental and hygienic laws and regulations

OTHER PRECAUTIONS

- 1. When an OLED display module is operated for a long of time with fixed pattern may remain as an after image or slight contrast deviation may occur. Nonetheless, if the operation is interrupted and left unused for a while, normal state can be restored. Also, there will be no problem in the reliability of the module
- To protect OLED display modules from performance drops by static electricity rapture, etc., do not touch the following sections whenever possible while handling the OLED display modules
 - Pins and electrodes
 - · Pattern layouts such as the TCP and FPC
- 3. With this OLED display module, the OLED driver is being exposed. Generally speaking, semiconductor elements change their characteristics when light is radiated according to the principle of the solar battery. Consequently, if this OLED driver is exposed to light, malfunctioning may occur
 - Design the product and installation method so that the OLED driver may be shielded from light in actual usage
 - Design the product and installation method so that the OLED driver may be shielded from light during the inspection processes

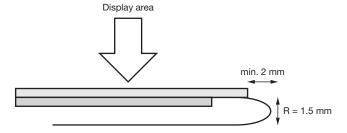
VISHAY.

OLED-256Y064B-LPP3N00000

Vishay

www.vishay.com

- 4. Although this OLED display module stores the operation state data by the commands and the indication data, when excessive external noise, etc. enters into the module, the internal status may be changed. It therefore is necessary to take appropriate measures to suppress noise generation or to protect from influences of noise on the system design
- 5. We recommend you to construct its software to make periodical refreshment of the operation statuses (re-setting of the commands and re-transference of the display data) to cope with catastrophic noise
- 6. Resistors, capacitors, and other passive components will have different appearance and color caused by the different supplier
- 7. Our company will has the right to upgrade and modify the product function
- 8. The limitation of FPC bending





Legal Disclaimer Notice

Vishay

Disclaimer

ALL PRODUCT, PRODUCT SPECIFICATIONS AND DATA ARE SUBJECT TO CHANGE WITHOUT NOTICE TO IMPROVE RELIABILITY, FUNCTION OR DESIGN OR OTHERWISE.

Vishay Intertechnology, Inc., its affiliates, agents, and employees, and all persons acting on its or their behalf (collectively, "Vishay"), disclaim any and all liability for any errors, inaccuracies or incompleteness contained in any datasheet or in any other disclosure relating to any product.

Vishay makes no warranty, representation or guarantee regarding the suitability of the products for any particular purpose or the continuing production of any product. To the maximum extent permitted by applicable law, Vishay disclaims (i) any and all liability arising out of the application or use of any product, (ii) any and all liability, including without limitation special, consequential or incidental damages, and (iii) any and all implied warranties, including warranties of fitness for particular purpose, non-infringement and merchantability.

Statements regarding the suitability of products for certain types of applications are based on Vishay's knowledge of typical requirements that are often placed on Vishay products in generic applications. Such statements are not binding statements about the suitability of products for a particular application. It is the customer's responsibility to validate that a particular product with the properties described in the product specification is suitable for use in a particular application. Parameters provided in datasheets and / or specifications may vary in different applications and performance may vary over time. All operating parameters, including typical parameters, must be validated for each customer application by the customer's technical experts. Product specifications do not expand or otherwise modify Vishay's terms and conditions of purchase, including but not limited to the warranty expressed therein.

Hyperlinks included in this datasheet may direct users to third-party websites. These links are provided as a convenience and for informational purposes only. Inclusion of these hyperlinks does not constitute an endorsement or an approval by Vishay of any of the products, services or opinions of the corporation, organization or individual associated with the third-party website. Vishay disclaims any and all liability and bears no responsibility for the accuracy, legality or content of the third-party website or for that of subsequent links.

Vishay products are not designed for use in life-saving or life-sustaining applications or any application in which the failure of the Vishay product could result in personal injury or death unless specifically qualified in writing by Vishay. Customers using or selling Vishay products not expressly indicated for use in such applications do so at their own risk. Please contact authorized Vishay personnel to obtain written terms and conditions regarding products designed for such applications.

No license, express or implied, by estoppel or otherwise, to any intellectual property rights is granted by this document or by any conduct of Vishay. Product names and markings noted herein may be trademarks of their respective owners.